

Atty. Docket No. PIA31221/DBE/US

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF:

:

Kyung Hee KOH

: GROUP ART UNIT:

SERIAL NO: NEW APPLICATION

:

FILED: HEREWITH

: EXAMINER:

FOR: Method for Packaging a Multi-Chip Module of a Semiconductor Device

I hereby certify that this document is being deposited with the United States Postal Service as Express Mail No. EU713645936US in an envelope addressed to Commissioner for Patents, Washington, D.C. 20231, on December 30, 2003.

By:


Jennie Heaton

REQUEST FOR PRIORITY UNDER 35 U.S.C. 119(a)-(b) AND 37 C.F.R. 1.55

COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

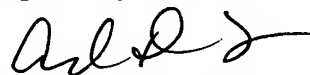
SIR:

Applicant respectfully requests under the Paris Convention for the Protection of Intellectual Property the benefit of the filing date of the prior foreign application(s) identified below:

<u>Serial No.</u>	<u>Filing Date</u>	<u>Country of Filing</u>
10-2002-0086243	December 30, 2002	Republic of KOREA

A certified copy of the priority application will be filed before any U.S. patent issues from the above-captioned application.

Respectfully submitted,


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